

SSM P/N LCC03259

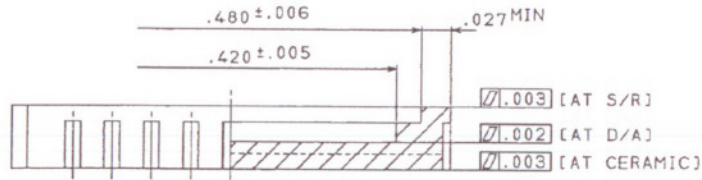
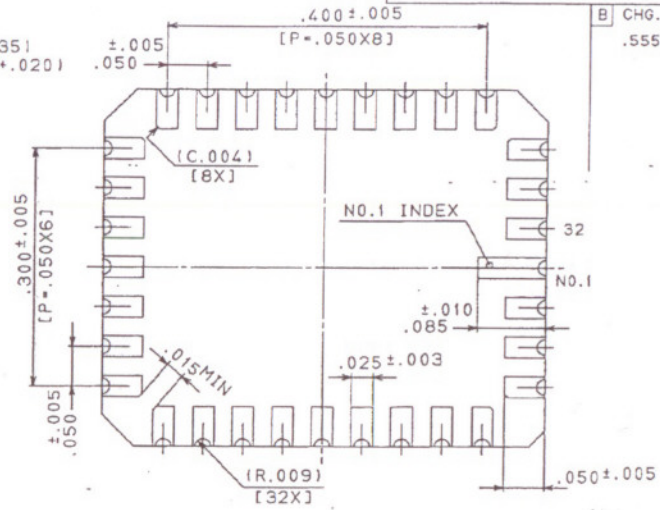
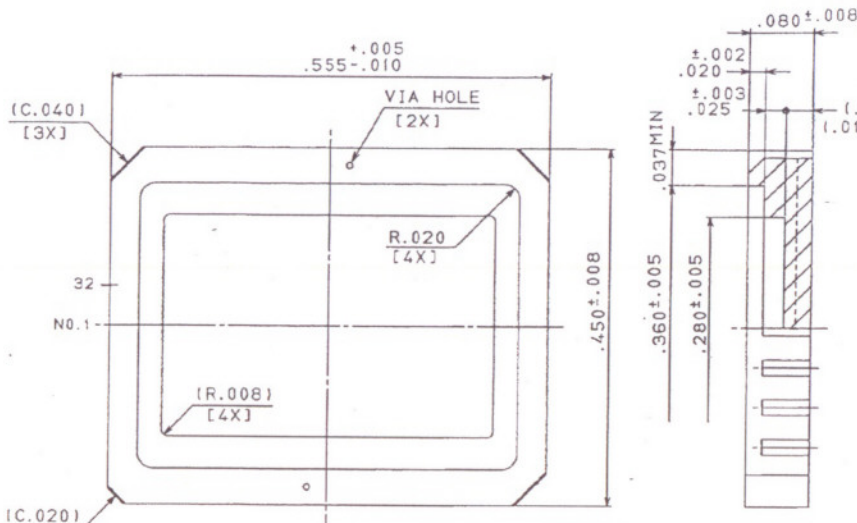
NTK

TECHNICAL CERAMICS

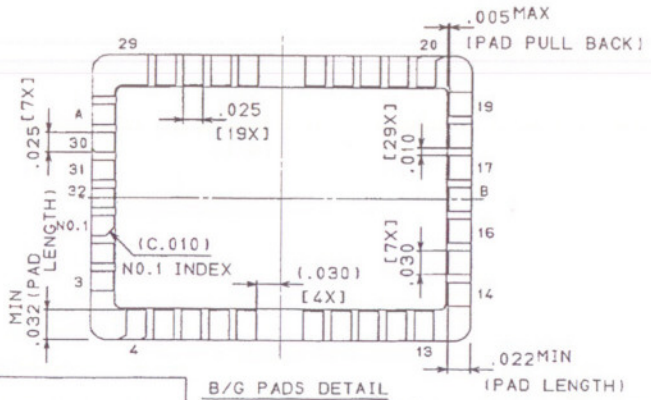
LATEST REVISION'S DESCRIPTION

A CHG. PKG C.D. .550±.008 WAS .555±.008
 CHG. CERAMIC THK
 .020/.025/.035 WAS .020/.020/.040
 CHG. CONTACT PAD LENGTH
 .050±.005 WAS .050±.006

B CHG. PKG LENGTH
 +.005
 .555±.010 WAS
 .550±.008



- NOTES: 1. GOLD PLATE 100μ INCHES MIN OVER 80μ INCHES MIN NICKEL.
 2. PAD NO.32.A & B TO BE CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.
 3. LEAD RESISTANCE : 500 mΩ MAX



発行
 7.9.12
 技術部

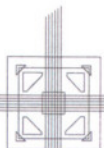
3				B	RE DRAWING	9-7-1995
2				A	RE DRAWING	9-1-1995
1	CERAMIC	BLACK ALUMINA		φ	NEW DRAWING	8-23-1995
Item	Material	Description	Rev.	Date		
UNLESS OTHERWISE SPECIFIED			DRAWN	H. OHIKE		
TOLERANCES: ± 1%			CHECKED	NTK TECHNICAL CERAMICS		
N. L. T. 2 DECIMALS. XX ± 01				NGK SPARK PLUG CO., LTD		
3 DECIMALS. XXX ± 005				TITLE		
CUSTOMER	ASJ	APPROVED	J. WASHINO	32 LEAD CHIP CARRIER		
DWG NO.		UNIT	INCH	DWG NO.		SIZE
		SCALE				A2
						AC

MODIFIED DWG NO.

B/G PADS DETAIL

IPAD PULL BACK!
 .005MAX
 IPAD LENGTH)
 .022MIN

PART NO. SHEET 1 OF 1 M·H



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